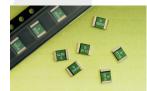


# 0ZCC1006D



Application All high-density boards

Product Features

1812 Chip Size, Fast Trip Time, Low DCR Resistance

**Operating (Hold Current) Range** 500mA ~ 1.1A

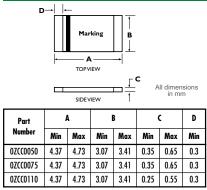
Maximum Voltage 6 ~ 16V (per table)

Temperature Range

-40°C to 85°C

Agency Approval UL Component (E305051)

## **Product Dimensions**



# Standard Package

2,000 fuses in 7 inches dia. reel, 8mm wide tape, 4mm pitch, per EIA-481 (equivalent IEC-286 part 3). P/N code - 2C.

# PTC Marking

**"bel**" or "**b**", Ін code.

# defining a degree of excellence

# Surface Mount PTC

1812 Chip RoHS6 Compliant

# 0ZCC Series

# Electrical Characteristics (23 ° C)

	<b>.</b> .	Hold Current	Trip Current	Max Time to Trip		Max Current	Rated Voltage	Typical Power	Resistance Tolerance		
	Part Number								Rmin	Rmax	R1 max
		IH, A	It, A	Current, A	Seconds	Imax, A	Vmax, Vdc	Pd, W	Ohms	Ohms	Ohms
A	0ZCC0050	0.50	1.0	8	0.15	40	16	0.8	0.15	0.57	1.00
B	0ZCC0075	0.75	1.5	8	0.02	40	16	0.8	0.11	0.27	0.45
C	0ZCC0110	1.10	2.2	8	0.30	40	6	0.8	0.04	0.11	0.21

IH Hold current-maximum current at which the device will not trip in still air at 23°C.

IT Trip current-minimum current at which the device will always trip in still air at 23°C.

Imax Maximum fault current device can withstand without damage at rated voltage (Vmax).

Vmax Maximum voltage device can withstand without damage at its rated current.

Pd Typical power dissipated from device when in the tripped state in 23°C still air environment.

- Rmin Minimum device resistance at 23°C.
- **R**max Maximum device resistance at 23°C.

R1max Maximum device resistance at 23°C, 1 hour after initial device trip.

# Termination pad characteristics

Termination pad materials

Tin-plated copper

# Pad Layout, Solder Reflow and Rework Recommendations

The dimensions in the table below provide the recommended pad layout for each OZCC device



Non	A ninal	Non	B 1inal	C Nominal		
mm	inch	mm	inch	mm	inch	
3.45	0.1358	1.78	0.0701	3.50	0.1378	

#### Solder Reflow

\* Due to "lead free/RoHS6" construction of these PTC devices, the required Temperature and Dwell Time in the "Soldering" zone of the reflow profile are greater than those used for non-RoHS devices.



- 1. Recommended reflow methods; IR , vapor phase oven, hot air oven.
- 2. The OZCC Series is suitable for wave solder application methods.
- 3. Recommended maximum paste thickness is 0.25mm.
- 4. Devices are compatible with standard industry cleaning solvents and methods.

#### **Caution**

If reflow temperature/dwell times exceed the recommended Profile, the electrical performance of the PTC may be affected.

#### Rework

Use standard industry practices.

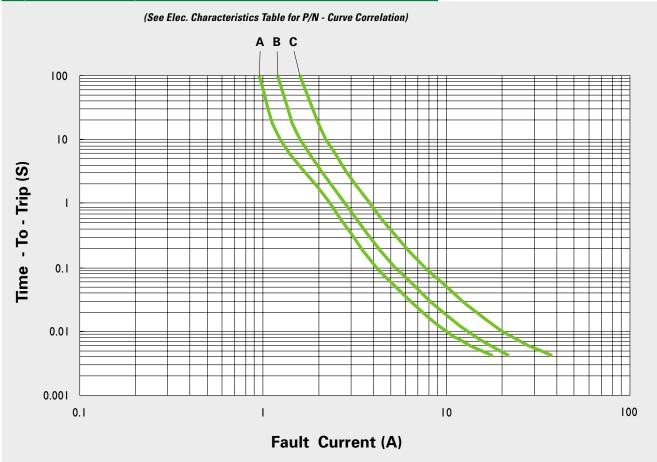
# defining a degree of excellence

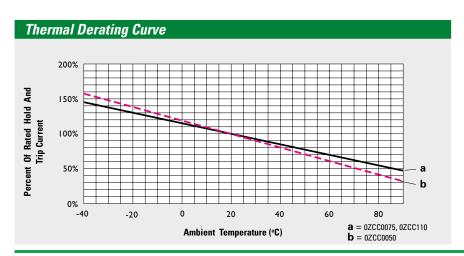
1812 Chip RoHS6 Compliant 0ZCC1006C

# 0ZCC Series

# *Typical Time -To - Trip at 23 ° C*

Surface Mount PTC





## Corporate Office

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#### **Cautionary Notes**

- 1. Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
- These Polymer PTC (PPTC) devices are intended for protection against occasional overcurrent/ overtemperature fault conditions and may not be suitable for use in applications where repeated and/ or prolonged fault conditions are anticipated.
- Avoid contact of PTC device with chemical solvent. Prolonged contact may adversely impact the PTC performance.
- These PTC devices may not be suitable for use in circuits with a large inductance, as the PTC trip can generate circuit voltage spikes above the PTC rated voltage.

Specifications subject to change without notice

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